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Date: 12/22/05

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Attorney's Docket No.: JG-SU-5222/500577.20072

U.S. Application No.:

International Application No.: PCT/JP2004/016001

International Filing Date: OCTOBER 28, 2004

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Priority Date Claimed: DECEMBER 01, 2003

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Title of Invention:

MANUFACTURING METHOD OF SILICON WAFER

Applicant(s) for (DO/EO/US):

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PRELIMINARY AMENDMENT

Sir:

The above-identified application is filed concurrently herewith, please amend the specification as follows:

Amendments to the specification begin on page 2 of this paper.

Amendments to the Abstract begin on page 3 of this paper.

Remarks / Arguments begin on page 8 of this paper.